



**Alfa-MOS
Technology**

**AFN5808W
20V N-Channel
Enhancement Mode MOSFET**

General Description

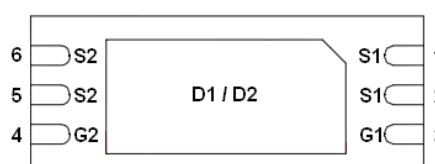
AFN5808W, N-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent $R_{DS(ON)}$, low gate charge.

These devices are particularly suited for low voltage power management, such as smart phone and notebook computer and other battery powered circuits, and low in-line power loss are needed in commercial industrial surface mount applications.

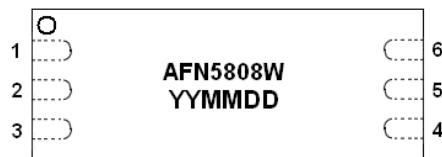
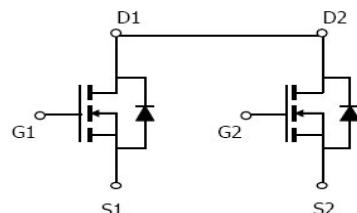
Features

- 20V/6.2A, $R_{DS(ON)}=32m\Omega$ @ $V_{GS}=4.5V$
- 20V/4.6A, $R_{DS(ON)}=38m\Omega$ @ $V_{GS}=2.5V$
- 20V/3.8A, $R_{DS(ON)}=50m\Omega$ @ $V_{GS}=1.8V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- DFN2X5-6L package design

Pin Description (DFN2X5-6L)



BOTTOM VIEW



TOP VIEW

Application

- Load Switch
- Portable Equipment
- Battery Powered System

Pin Define

Pin	Symbol	Description
1	S1	Source1
2	S1	Source1
3	G1	Gate1
4	G2	Gate2
5	S2	Source2
6	S2	Source2

Ordering Information

Part Ordering No.	Part Marking	Package	Unit	Quantity
AFN5808WFN256RG	AFN5808W YYMMDD	DFN2X5-6L	Tape & Reel	2500 EA

※ YY year code

※ MM month code

※ DD date code

※ AFN5808WFN256RG : 7" Tape & Reel ; Pb- Free ; Halogen- Free



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Absolute Maximum Ratings

($T_A=25^\circ\text{C}$ Unless otherwise noted)

Parameter	Symbol	Typical	Unit
Drain-Source Voltage	V_{DSS}	20	V
Gate –Source Voltage	V_{GSS}	± 12	V
Continuous Drain Current($T_J=150^\circ\text{C}$)	I_D	6.2	A
$T_A=70^\circ\text{C}$		3.8	
Pulsed Drain Current	I_{DM}	40	A
Continuous Source Current(Diode Conduction)	I_S	1.6	A
Power Dissipation	P_D	1.6	W
$T_A=70^\circ\text{C}$		1.0	
Operating Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55/150	$^\circ\text{C}$
Thermal Resistance-Junction to Ambient	$R_{\theta JA}$	120	$^\circ\text{C}/\text{W}$

Electrical Characteristics

($T_A=25^\circ\text{C}$ Unless otherwise noted)

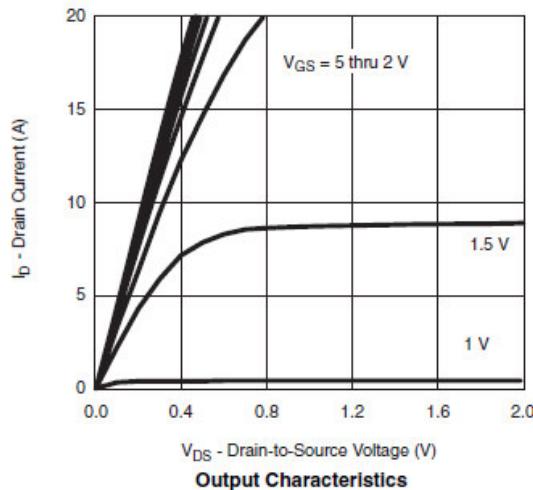
Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	20			V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	0.3		0.8	
Gate Leakage Current	I_{GSS}	$V_{DS}=0\text{V}, V_{GS}=\pm 12\text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=16\text{V}, V_{GS}=0\text{V}$			1	uA
		$V_{DS}=16\text{V}, V_{GS}=0\text{V}$ $T_J=85^\circ\text{C}$			10	
On-State Drain Current	$I_{D(on)}$	$V_{DS} \geq 5\text{V}, V_{GS}=4.5\text{V}$	6			A
		$V_{DS} \geq 5\text{V}, V_{GS}=2.5\text{V}$	4			
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=4.5\text{V}, I_D=6.2\text{A}$		26	32	m Ω
		$V_{GS}=2.5\text{V}, I_D=4.6\text{A}$		31	38	
		$V_{GS}=1.8\text{V}, I_D=3.8\text{A}$		43	50	
Forward Transconductance	g_{FS}	$V_{DS}=5\text{V}, I_D=3.6\text{A}$		10		S
Diode Forward Voltage	V_{SD}	$I_S=1.6\text{A}, V_{GS}=0\text{V}$		0.85	1.2	V
Dynamic						
Total Gate Charge	Q_g	$V_{DS}=10\text{V}, V_{GS}=4.5\text{V}$ $I_D=6.2\text{A}$		6.2	10	nC
Gate-Source Charge	Q_{gs}			1.0		
Gate-Drain Charge	Q_{gd}			1.6		
Input Capacitance	C_{iss}	$V_{DS}=10\text{V}, V_{GS}=0\text{V}$ $f=1\text{MHz}$		480		pF
Output Capacitance	C_{oss}			160		
Reverse Transfer Capacitance	C_{rss}			100		
Turn-On Time	$t_{d(on)}$	$V_{DD}=10\text{V}, R_L=1.9\Omega$ $I_D=5.4\text{A}, V_{GEN}=4.5\text{V}$ $R_G=1\Omega$		10	16	ns
	t_r			12	25	
Turn-Off Time	$t_{d(off)}$			25	40	
	t_f			12	20	



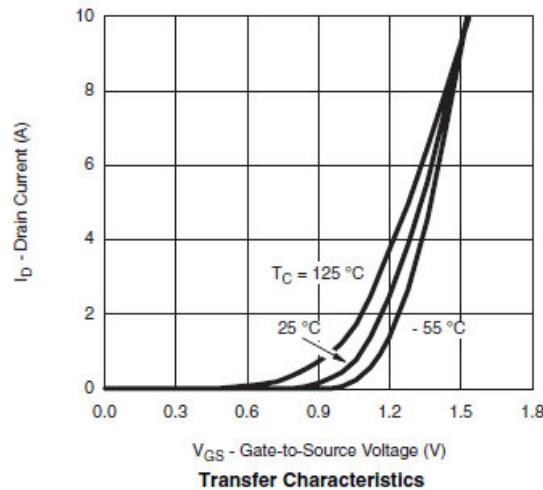
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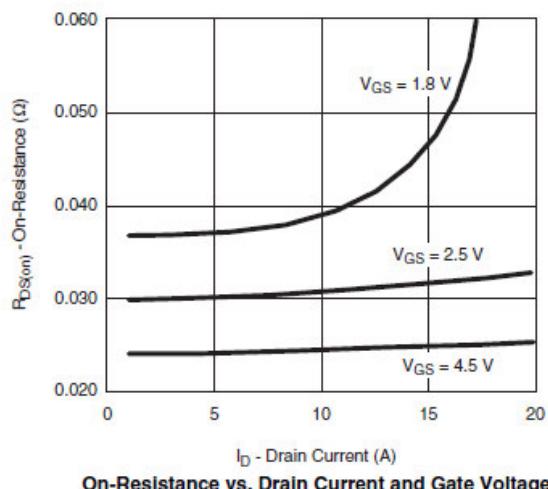
Typical Characteristics



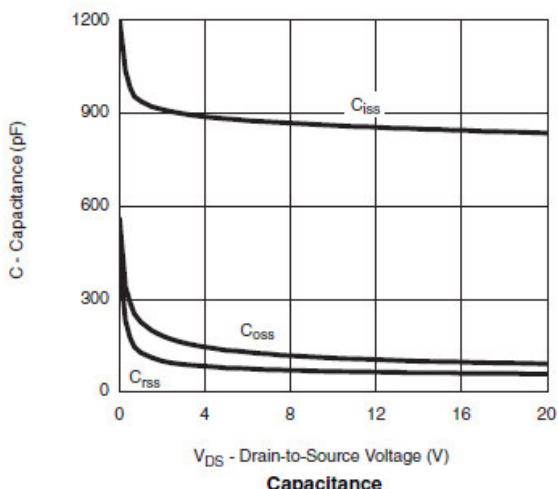
Output Characteristics



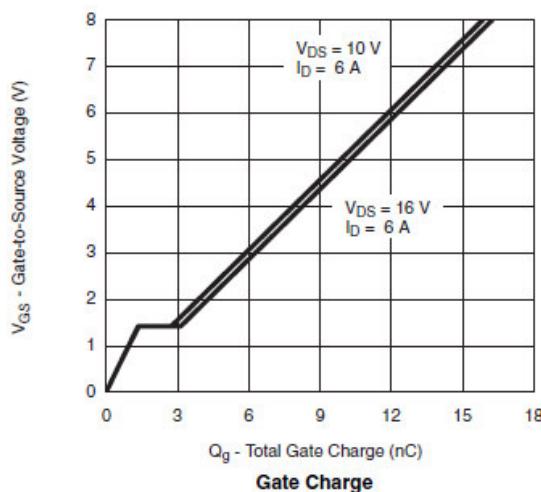
Transfer Characteristics



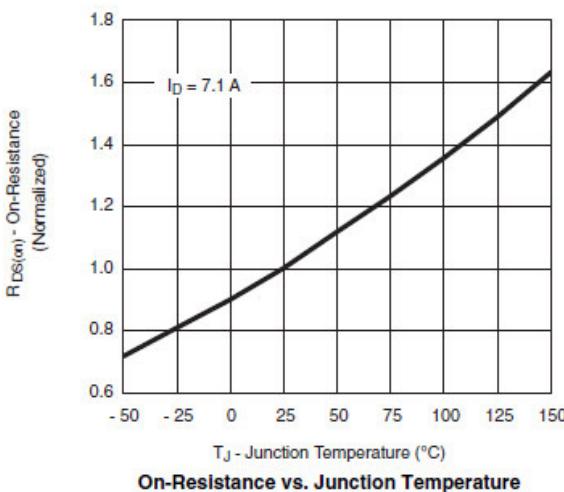
On-Resistance vs. Drain Current and Gate Voltage



Capacitance



Gate Charge



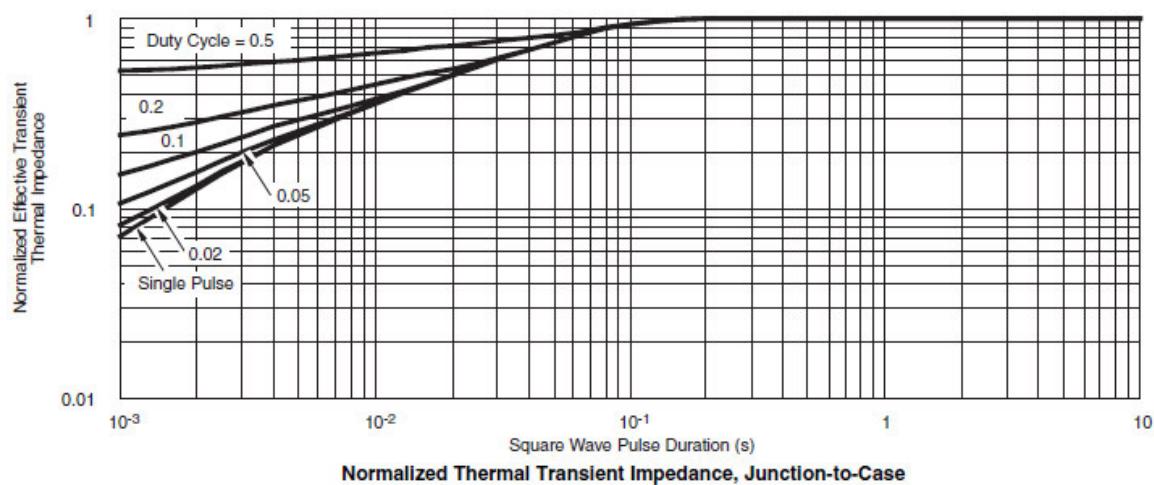
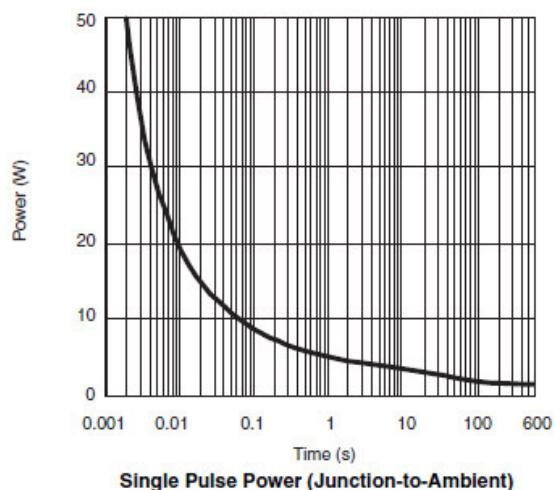
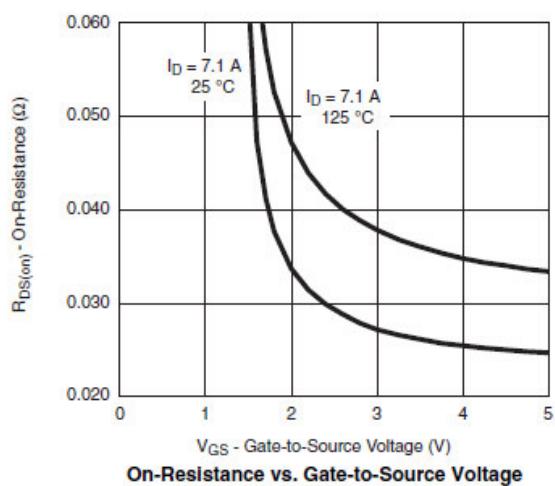
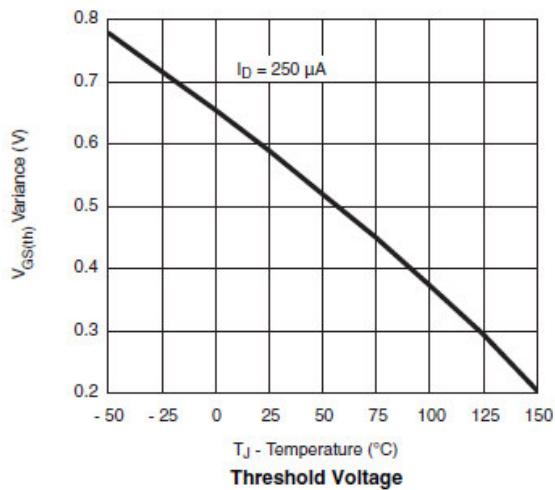
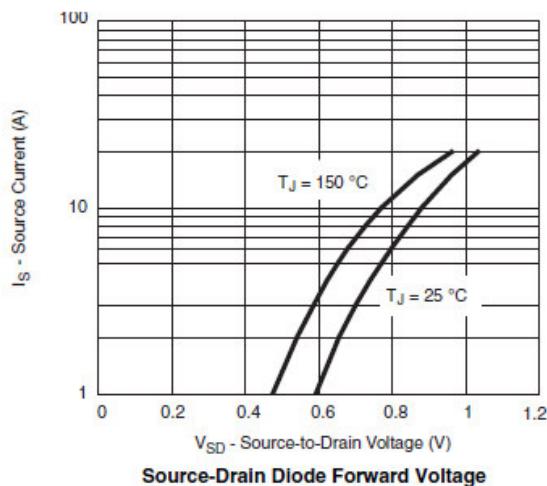
On-Resistance vs. Junction Temperature



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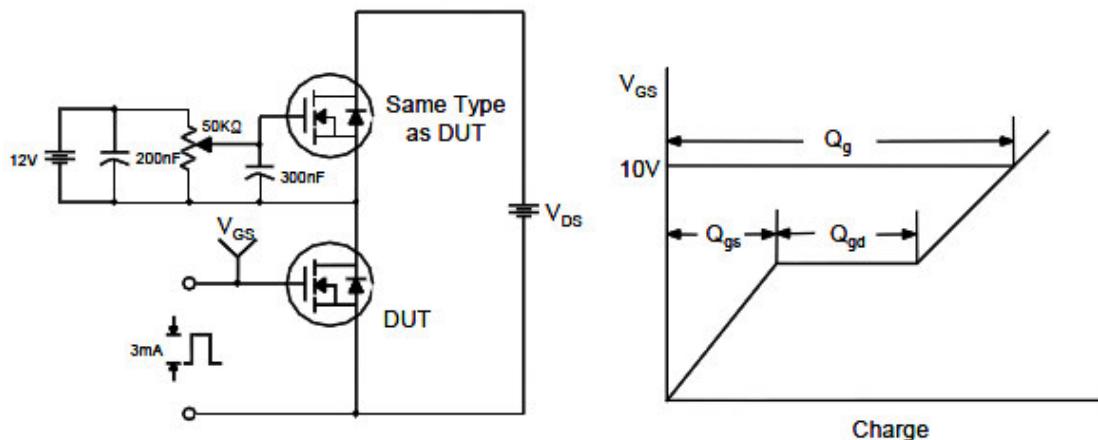


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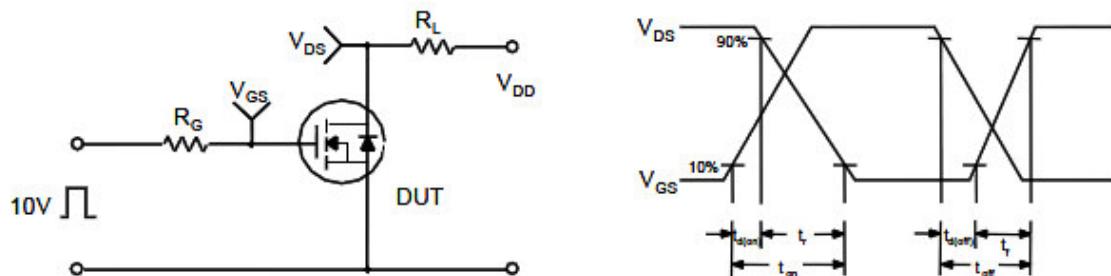
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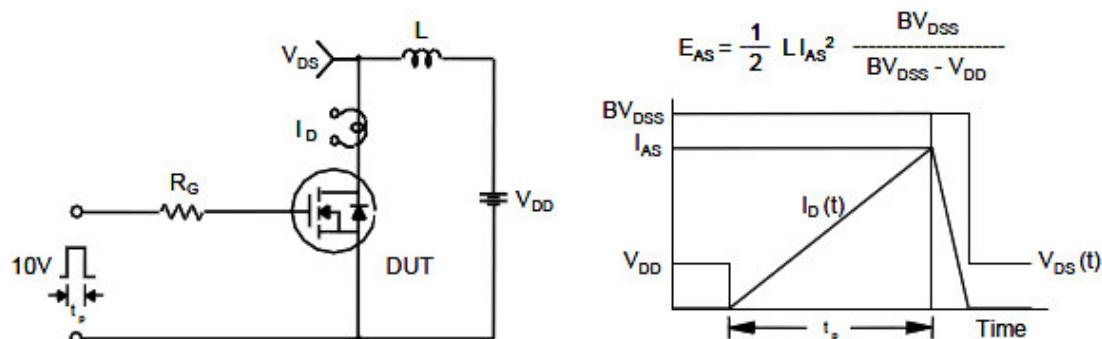
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms

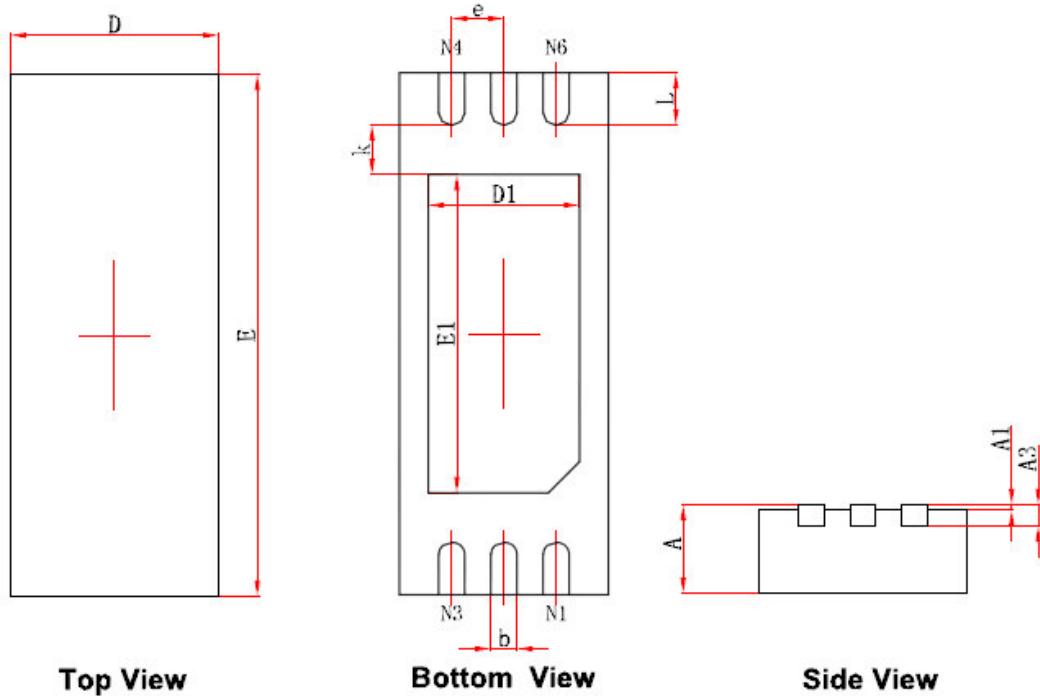




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Package Information (DFN2X5-6L)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.800	0.028	0.031
A1	0.000	0.050	0.000	0.002
A3	0.203REF.		0.008REF.	
D	1.924	2.076	0.076	0.082
E	4.924	5.076	0.194	0.200
D1	1.350	1.550	0.053	0.061
E1	2.950	3.150	0.116	0.124
k	0.200MIN.		0.008MIN.	
b	0.200	0.300	0.008	0.012
e	0.500TYP.		0.020TYP.	
L	0.424	0.576	0.017	0.023

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